## Product End-of-Life Disassembly Instructions

**Product Category:** Personal Computers  

**Marketing Name / Model**  
[List multiple models if applicable.]  
HP ap5000 All-in-One Point of Sale System

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

### 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.  
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>3 (system board; HDD board; PCI board)</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>1</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>2</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td>system fan, psu fan, heatsink fan</td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
</tbody>
</table>

PSG instructions for this template are available at [EL-MF877-01](#)
Components and waste containing asbestos | 0
Components, parts and materials containing refractory ceramic fibers | 0
Components, parts and materials containing radioactive substances | 0

2.0 Tools Required
List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Torx Screw Driver</td>
<td>0</td>
</tr>
<tr>
<td>Philips #2 Screw Driver</td>
<td>1</td>
</tr>
<tr>
<td>Dikes Pliers (picture 15)</td>
<td>1</td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Step 1~5 : Remove VFD module.
2. Step 6~7 : Remove Counter Base Assembly
4. Step 11 : HDD Door and Side IO Cover.
5. Step 12~13 : Remove Back Cover Assembly.
7. Step 21~23 : Remove PCI board.
8. Step 24~27 : Remove Inverter board.
9. Step 28~34 : Take apart LCD Assembly.
10. Step 35~36 : Take apart MSR Assembly.
12. Step 43~51 : Take apart Base Assembly.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Pull the cover both sides to remove it.

Release two screws fixing VFD hinge with system.
Click these two tabs to open IO cover.

Take off COM port plug.
5. Pull the VFD assembly upward to take off it.

6.1. Release one screw from base cover back.

6.2. Take off Power Jack

6.3. Release another screw from base cover bottom.
Pull the base unit downward to remove it.

Remove Circular Mylar from screw hole.
Release 2 pcs screw to take off MSR module from system.

Take off MSR Cable
11. Release HDD Door screw to take off HDD Door and Side IO Cover.

12. Release 4 pcs screw which is used to fix Back cover with Front Cover.
Take off Back Cover

Take off HDD and HDD carrier.

HDD and HDD carrier
Take off Air Duct

Release 3 pcs screws to take off Fan module from MB.
Take off Fan plugs and Remove Fan Module

Take off Plug
Release 4 pcs screws to take off MB Module from LCD bracket.

Pull the MB Module downward to take off it.
21 Take off all cables from PCI PCB.

Open the Mylar covered on PCI.

Remove all Cables

22 Cut out cable tie by Dikes Pliers.
Release 2 pcs screws to Remove PCI PCB.

Take off two pcs of Cable.
Release 3 pcs screws to Remove Inverter EMI bracket.

Release 3 pcs screws fixing Inverter PCB.
27. Take off cable to remove Inverter PCB.

28. Release 4 pcs screws fixing LCD bracket with Front Cover.
Take off connectivity of touch panel cable.

Take off LCD module from Front Cover Assembly.
Release 4 pcs screws to take off LCD panel from LCD bracket.

LCD panel

LCD bracket
Take off all cables from LCD bracket.

- Touch Panel cable
- Inverter Cable
- MSR cable
- Speaker Cable

Disassemble Front Cover Assembly

- Front seal rubber
- Touch panel
- Front Cover
- LED cable
Click MSR side wall to take off MSR back cover.

Release two screws to take off MSR module and bracket from MSR front cover.
Release four screws to take off VFD front cover.

Un-connect VFD cable and take off VFD Module.
Pull out VFD cable through VFD back cover and Hinge.

Click red circle area to take off Hinge cover.

PSG instructions for this template are available at EL-MF877-01
Release 2 pcs fixing Hinge bracket with MSR back cover.

Pull VFD hinge bracket downward to remove it.
Pull silver AD panel both side to remove it.

Take off base ear both side.

PSG instructions for this template are available at EL-MF877-01
45 Release 3 pcs screws both side and Take off base cover and base hinge.

46 Release thumb screw fixing adapter bracket with Stand.
47 Take off adapter bracket and adapter from base assembly.

48 Release four screws to take off stand foot rubber
49 Release two screws at bottom side.

50 Take off two rubber covers and Release two screws.

PSG instructions for this template are available at EL-MF877-01
51. Take apart Base assembly

Base Cap

Stand Bracket

Base

52. Release 3 pcs screws to take off HDD Cage(with HDD back PCB) and HDD plate

HDD Cage

HDD plate
53 Take off HDD board and Cage bracket

Release 4 pcs screws

HDD board

Cage bracket

54 Take off Heat Sink and back plate by releasing four screws.

Release 4 pcs screws

Heat Sink

Back Plate
At back side of MB.
55. Take off CPU.

56. Release 10 pcs of Hexagon screw to take off IO Bracket and MB.

PSG instructions for this template are available at EL-MF877-01